

L Number	Hits	Search Text	DB	Time stamp
1	1396	wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 14:06
2	1056	(wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support))) and (@ad<20010601)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 14:07
3	399	((wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support))) and (@ad<20010601)) and (Wafer near (via or thru or through or hole or holes or vias or opening or open or gap))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 12:51
4	207	((wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support))) and (@ad<20010601)) and (Wafer near (via or thru or through or hole or holes or vias or opening or open or gap))) and (Wafer near silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 14:03
5	35	5286671.URPN.	USPAT	2004/04/29 13:57
6	0	438/464.ccls. and beol	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 14:05
7	1	((wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support))) and (@ad<20010601)) and (Wafer near (via or thru or through or hole or holes or vias or opening or open or gap))) and (beol or (back near line))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 14:04
8	8646	((@ad<20010601) and (beol or (back near line))) and (wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 14:04
9	3	((@ad<20010601) and (beol or (back near line))) and (wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 14:05
10	2	438/464.ccls. and (back near line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 14:06
11	46	((@ad<20010601) and (beol or (back near line))) and (wafer with (holder or handle or temporary or support))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 14:07
12	46	((@ad<20010601) and (beol or (back near line))) and (wafer with (holder or handle or temporary or support))) and (@ad<20010601)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 14:07